**ON Semiconductor** 

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# Onsemí

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# **Dual Unbuffered Inverter**

The NLU2GU04 MiniGate<sup>™</sup> is an advanced high–speed CMOS dual unbuffered inverter in ultra–small footprint.

This device is well suited for use in oscillator, pulse–shaping and high input impedance amplifier applications. For digital applications, the NLU2G04 is recommended.

The NLU2GU04 input and output structures provide protection when voltages up to 7 V are applied, regardless of the supply voltage.

#### Features

- High Speed:  $t_{PD} = 2.5 \text{ ns} (Typ) @ V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 1 \ \mu A$  (Max) at  $T_A = 25^{\circ}C$
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra-Small Packages
- These are Pb–Free Devices

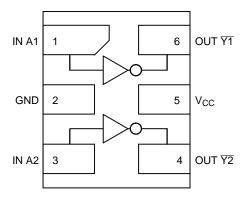
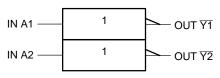


Figure 1. Pinout (Top View)





**PIN ASSIGNMENT** 

IN A1
GND
IN A2
OUT Y2
V <sub>CC</sub>
OUT Y1

FUNCTION TABLE					
Α	Ŧ				
L H	H L				



# **ON Semiconductor®**

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MARKING DIAGRAMS UDFN6 1.0 x 1.0 XΜ CASE 517BX UDFN6 MU SUFFIX ΝМ CASE 517AA UDFN6 ΧM 1.45 x 1.0 0 CASE 517AQ **ULLGA6** ZM 1.2 x 1.0 CASE 613AE Z or 3 = Device Marking = Date Code М

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

#### MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage	-0.5 to +7.0	V	
V <sub>OUT</sub>	DC Output Voltage		-0.5 to +7.0	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < GND	-20	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < GND	±20	mA
Ι <sub>Ο</sub>	DC Output Source/Sink Current	±12.5	mA	
I <sub>CC</sub>	DC Supply Current Per Supply Pin	±25	mA	
I <sub>GND</sub>	DC Ground Current per Ground Pin	±25	mA	
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C	
ΤL	Lead Temperature, 1 mm from Case for 10 Second	ds	260	°C
TJ	Junction Temperature Under Bias	150	°C	
MSL	Moisture Sensitivity	Level 1		
F <sub>R</sub>	Flammability Rating Oxygen	UL 94 V–0 @ 0.125 in		
ILATCHUP	Latchup Performance Above $V_{CC}$ and Below GND	±500	mA	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.
Tested to EIA / JESD78.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage	1.65	5.5	V
V <sub>IN</sub>	Digital Input Voltage	0	5.5	V
V <sub>OUT</sub>	Output Voltage	0	5.5	V
T <sub>A</sub>	Operating Free–Air Temperature	-55	+125	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0	100 20	ns/V

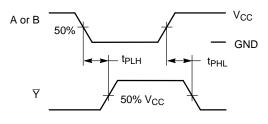
#### DC ELECTRICAL CHARACTERISTICS

			nditions V <sub>CC</sub> (V)	T <sub>A</sub> = 25 °C		T <sub>A</sub> = +	⊦85°C		55°C to 5°C		
Symbol	Parameter	Conditions		Min	Тур	Max	Min	Max	Min	Max	Unit
V <sub>IH</sub>	Low–Level Input Voltage		1.65 2.3 to 5.5	0.85 x V <sub>CC</sub> 0.80 x V <sub>CC</sub>			0.85 x V <sub>CC</sub> 0.80 x V <sub>CC</sub>				V
V <sub>IL</sub>	Low–Level Input Voltage		1.65 2.3 to 5.5			0.15 x V <sub>CC</sub> 0.20 x V <sub>CC</sub>		0.15 x V <sub>CC</sub> 0.20 x V <sub>CC</sub>		0.15 x V <sub>CC</sub> 0.20 x V <sub>CC</sub>	V
V <sub>OH</sub>	High–Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -50 μA	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -4 \text{ mA}$ $I_{OH} = -8 \text{ mA}$	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		
V <sub>OL</sub>	Low–Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50 \ \mu\text{A}$	2.0 3.0 4.5		0 0 0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I <sub>IN</sub>	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I <sub>CC</sub>	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5.5			1.0		20		40	μΑ

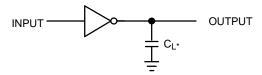
#### **AC ELECTRICAL CHARACTERISTICS** (Input $t_r = t_f = 3.0 \text{ ns}$ )

		V <sub>CC</sub>	Vcc Test		A = 25 °	c	<b>T</b> <sub>A</sub> = -	⊦85°C	T <sub>A</sub> = - to +1	-55°C 25°C	
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub> ,		3.0 to	C <sub>L</sub> = 15 pF		3.5	8.9		10.5		12	ns
<sup>I</sup> PHL		3.6	C <sub>L</sub> = 50 pF		4.8	11.4		13		15.5	
		4.5 to	C <sub>L</sub> = 15 pF		2.5	5.5		6.5		8.0	
		5.5	C <sub>L</sub> = 50 pF		3.8	7.0		8.0		9.5	
C <sub>IN</sub>	Input Capacitance				4	10		10		10	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 3)	5.0			22						pF

3.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$ .  $C_{PD}$  is used to determine the no–load dynamic power consumption:  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$ .







\*Includes all probe and jig capacitance. A 1–MHz square input wave is recommended for propagation delay tests.

#### Figure 4. Test Circuit

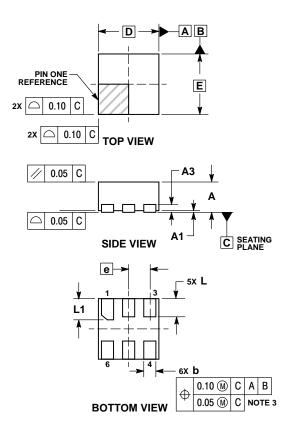
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>		
NLU2GU04MUTCG	UDFN6, 1.2 x 1.0, 0.4P (Pb–Free)	3000 / Tape & Reel		
NLU2GU04AMUTCG	ILU2GU04AMUTCG UDFN6, 1.45 x 1.0, 0.5P (Pb-Free)			
NLU2GU04CMUTCG	UDFN6, 1.0 x 1.0, 0.35P (Pb–Free)	3000 / Tape & Reel		
NLU2GU04BMX1TCG	ULLGA6, 1.2 x 1.0, 0.4P (Pb–Free)	3000 / Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

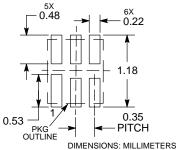
UDFN6 1.0x1.0, 0.35P CASE 517BX ISSUE O



- NOTES:
   DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
   CONTROLLING DIMENSION: MILLIMETERS.
   DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
   PACKAGE DIMENSIONS EXCLUSIVE OF BUIDES AND MOLD EI ASH ASH.

BURF	BURRS AND MOLD FL						
	MILLIMETERS						
DIM	MIN MAX						
Α	0.45 0.55						
A1	0.00	0.00 0.05					
A3	0.13 REF 0.12 0.22 1.00 BSC						
b							
D							
Е	1.00	BSC					
е	0.35	0.35 BSC					
L	0.25 0.35 0.30 0.40						
L1							

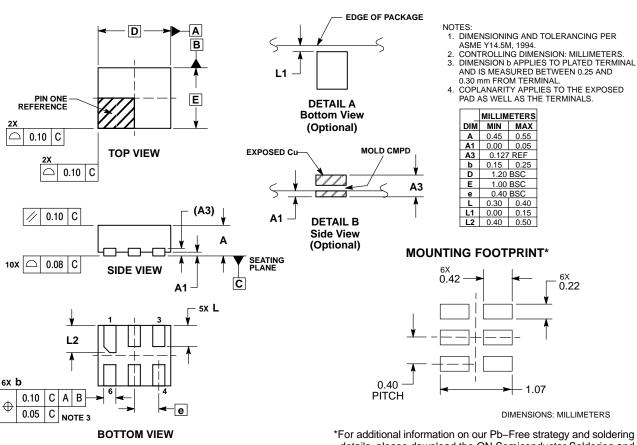
# RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

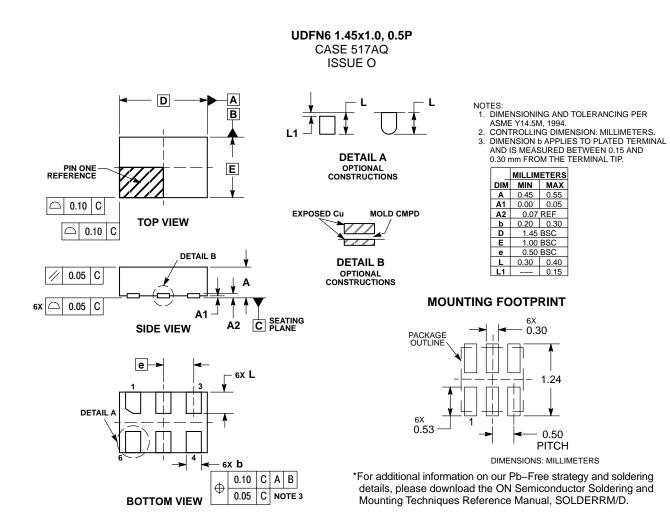
#### PACKAGE DIMENSIONS

UDFN6, 1.2x1.0, 0.4P CASE 517AA ISSUE C



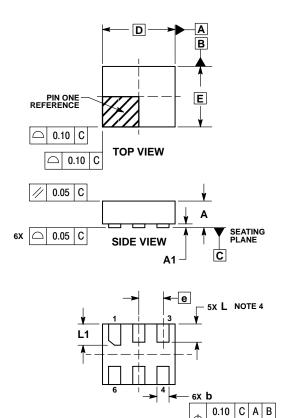
details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS



#### PACKAGE DIMENSIONS

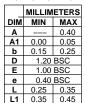
ULLGA6 1.2x1.0, 0.4P CASE 613AE **ISSUE A** 



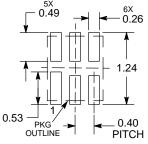
**BOTTOM VIEW** 

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. 2. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP. 3.
- 4 A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.



#### **MOUNTING FOOTPRINT** SOLDERMASK DEFINED



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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0.05 C NOTE 3

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